

SOT-363 Plastic-Encapsulate MOSFETS

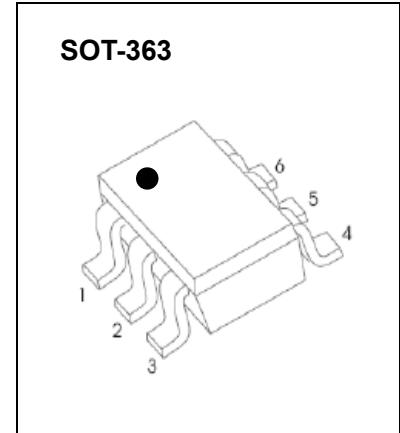
CJ7252KDW N Channel + P Channel Power MOSFET

DESCRIPTION

This N Channel + P Channel MOSFET has been designed using advanced power trench process to optimize the $R_{DS(ON)}$.

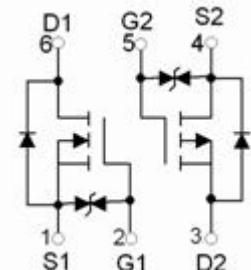
FEATURE

- High-Side Switching
- Low Threshold
- Fast Switching Speed
- Including a 2N7002K and a CJ502K MOSFET (independently) in a package



APPLICATION

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers



MARKING: 75

MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
N-Channel MOSFET			
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current -Continuous	0.34	A
I_{DM}	Drain Current - Pulsed(Note1)	1.36	A
P- Channel MOSFET			
V_{DS}	Drain-Source Voltage	-50	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current -Continuous	-0.18	A
I_{DM}	Drain Current – Pulsed (Note1)	-0.7	A
Power Dissipation, Temperature and Thermal Resistance			
P_D	Power Dissipation	0.15	W

$R_{\theta JA}$	Thermal Resistance from Junction to Ambient (Note2)	833	°C/W
T_J	Junction Temperature	150	°C
T_{stg}	Storage Temperature	-55~+150	°C
T_L	Lead Temperature	260	°C

ELECTRICAL CHARACTERISTICS ($T_a=25^\circ C$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
N- Channel MOSFET						
STATIC PARAMETERS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=48V, V_{GS}=0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 10	μA
		$V_{GS}=\pm 10V, V_{DS}=0V$			± 200	nA
		$V_{GS}=\pm 5V, V_{DS}=0V$			± 100	nA
Gate threshold voltage (note 3)	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=1mA$	1			V
Drain-source on-resistance (note 3)	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=0.2A$			5.3	Ω
		$V_{GS}=10V, I_D=0.5A$			5	Ω
Diode forward voltage	V_{SD}	$I_S=0.3A, V_{GS}=0V$			1.5	V
DYNAMIC PARAMETERS (note 4)						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V, f=1MHz$			40	pF
Output Capacitance	C_{oss}				30	pF
Reverse Transfer Capacitance	C_{rss}				10	pF
SWITCHING PARAMETERS (note 4)						
Turn-on delay time	$t_{d(on)}$	$V_{GS}=10V, V_{DD}=50V,$ $R_L=250\Omega, R_{GEN}=50\Omega,$			10	ns
Turn-off delay time	$t_{d(off)}$				15	ns
Reverse recovery time	t_{rr}	$I_S=300mA;$ $dI_S/dt=-100A/s; V_{GS}=0V;$ $V_R=25V$		30		ns
Recovered charge	Q_r			30		nC
P- Channel MOSFET						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-50			V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=-50V, V_{GS}=0V$			-15	μA
		$V_{DS}=-25V, V_{GS}=0V$			-0.1	μA
Gate-body leakage current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 10	nA
Gate threshold voltage (note 3)	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.9		-2	V

Drain-source on-resistance (note 3)	$R_{DS(on)}$	$V_{GS} = -5V, I_D = -0.1A$			10	Ω
		$V_{GS} = -10V, I_D = -0.1A$			8	Ω
Forward transconductance (note 3)	g_{FS}	$V_{DS} = -25V, I_D = -0.1A$	0.05			S
DYNAMIC CHARACTERISTICS (note 4)						
Input capacitance	C_{iss}	$V_{DS} = -5V, V_{GS} = 0V, f = 1MHz$		30		pF
Output capacitance	C_{oss}			10		pF
Reverse transfer capacitance	C_{rss}			5		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -15V,$ $R_L = 50\Omega, I_D = -2.5A$		2.5		ns
Turn-on rise time	t_r			1		ns
Turn-off delay time	$t_{d(off)}$			16		ns
Turn-off fall time	t_f			8		ns
SOURCE-DRAIN DIODE CHARACTERISTICS(note 4)						
Continuous Current	I_S				-0.18	A
Pulsed Current	I_{SM}				-0.7	A
Diode forward voltage (note 3)	V_{DS}	$I_S = -0.13A, V_{GS} = 0V$			-2.2	V

Note:

- 1、 Surface mounted on FR-4 board using minimum pad size, 1oz copper
- 2、 Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3、 Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 4、 These parameters have no way to verify.